



PK513 (v1.2) August 10, 2017

100% Material Declaration Data Sheet for Spartan®-3/-3E PQG208 (Cu Wire)

Average Weight :

5.4500 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon Die 1					0.029935	0.54927%
	Silicon	7440-21-3	100.00		0.029935	
Mold Compound					5.036337	92.40985%
	Silica Fused	60676-86-0	77.40		3.898125	
	Epoxy Resin	Trade Secret	7.00		0.352544	
	Phenol Resin	Trade Secret	5.00		0.251817	
	Carbon Black	1333-86-4	0.30		0.015109	
	Silica Fused	7631-86-9	10.00		0.503634	
	Silica, crystalline	14808-60-7	0.30		0.015109	
Die Attach					0.003992	0.07325%
	Silver	7440-22-4	73.00		0.002914	
	Epoxy Resin	Trade secret	13.50		0.000539	
	Anhydride	Trade Secret	10.50		0.000419	
Solder Plating					0.033200	0.60917%
	Tin	7440-31-5	100.00		0.033200	
Copper Wire					0.001737	0.03187%
	Copper	7440-50-8	97.28		0.001690	
	Palladium	5/3/7440	2.70		0.000047	
	Impurities	N/A	0.02		0.000000	
Leadframe					0.338799	6.21650%
	Copper	7440-50-8	94.40		0.319826	
	Magnesium	7439-95-4	0.18		0.000610	
	Nickel	7440-02-0	3.20		0.010842	
	Silicon	7440-21-3	0.73		0.002473	
Leadframe Tape					0.006000	0.11009%
	Polyimide	Trade secret	43.00		0.002580	
	Poly-ethylene-terephthalate	Trade secret	25.00		0.001500	
	NBR	Trade secret	12.00		0.000720	
	Bismaleimide	Trade secret	10.00		0.000600	
Phenol resin	Trade secret	10.00		0.000600		

Revision History

Date	Version	Description of Revisions
9/16/2011	1.0	Initial Xilinx release.
3/19/2012	1.1	Device family update.
8/10/2017	1.2	Update Leadframe Tape CAS# discription

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